

Applicant:

Harry A. ATWATER, Jr. et al.

Title:

WAFER BONDED VIRTUAL SUBSTRATE AND

METHOD FOR FORMING THE SAME

Appl. No.:

10/761,918

Filing Date:

1/20/2004

Examiner:

Duy-Vu DEO

Art Unit:

1765

Confirmation

4108

Number:

AMENDMENT AND REPLY UNDER 37 CFR 1.116

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

This communication is responsive to the Final Office Action dated November 7, 2006, concerning the above-referenced patent application.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this document.

Remarks/Arguments begin on page 5 of this document.

Please amend the application as follows: